

INSTRUCTIONS

ASSIGNMENT OF U.S. RIGHTS TO CORPORATION

WHEREAS,

Inventor(s) Name,
Address, Citizenship

1. Tetsuya OKANA residing at 5-26-207, Okaminamicho, Hirakata-shi, Osaka 573-0033, JAPAN and a citizen of JAPAN;
2. Mitsuhisa FUJIKI residing at 2-10-15, Higarigaoka, Ikoma-shi, Nara 630-0141, JAPAN and a citizen of JAPAN;
3. Satoshi YAMABAYASHI residing at 2-11-11, Hoshigaoka, Hirakata-shi, Osaka 573-0013, JAPAN and a citizen of JAPAN;
4. Shinya OGASAWARA residing at 6-11-103, Toukoucho 3-chome, Moriguchi-shi, Osaka 570-0035, JAPAN and a citizen of JAPAN;

Date Patent Declaration
Signed and Title Serial
No. and filing date (if
known)

(herein called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States on for this invention, which application is entitled

METHOD OF MANUFACTURING HEAD UNIT

and which has been given Serial No. __ and the filing date of __;

Name of Corporation

AND WHEREAS Matsushita Electric Industrial Co., Ltd. (herein called "ASSIGNEE"), a corporation organized under the laws of JAPAN, and having an office and place of business at 1006-banchi, Oaza-Kadoma, Kadoma-shi, Osaka 571-8501, JAPAN

State or Country of
Incorporation and Address

wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign and transfer to the ASSIGNEE, its successors and assigns, the entire right, title and interest for the United States in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE its successors and assigns, that no assignment grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Each inventor must sign & date

Tetsuya Oana
Signature

July 17, 2001
Date

Note: No legalization or other witness required

Mitsuhisa Fujiki
Signature

July 17, 2001
Date

Satoshi Yamabayashi
Signature

July 17, 2001
Date

Shinya Ogasawara
Signature

July 17, 2001
Date